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Application Number		10587725
Filing Date		2006-07-26
First Named Inventor	Etsuro MORITA	
Art Unit		2813
Examiner Name	Candice CHAN	
Attorney Docket Number		SHX 373

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/CC/	3	9320584	WO	A1	1993-10-14	Gassel et al.		☒

<table>
<tr><td>/CC/</td><td>4</td><td>07226433</td><td>JP</td><td></td><td>1995-08-22</td><td>Hashimoto</td><td></td><td>☒</td></tr>
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/CC/	1	GASSEL et al., "SIMOX and Wafer Bonding: Combination of Competitors Complements One Another." Abstract No. 847, 1046b Extended Abstracts, Spring Meeting (1993), pp. 1246-1247.	☐
/CC/	2	TONG et al., "VLSI SOI Fabrication by SIMOX Wafer Bonding (SWB)." Institute of Electrical and Electronics Engineers (1992), pp. 72-73.	☐
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